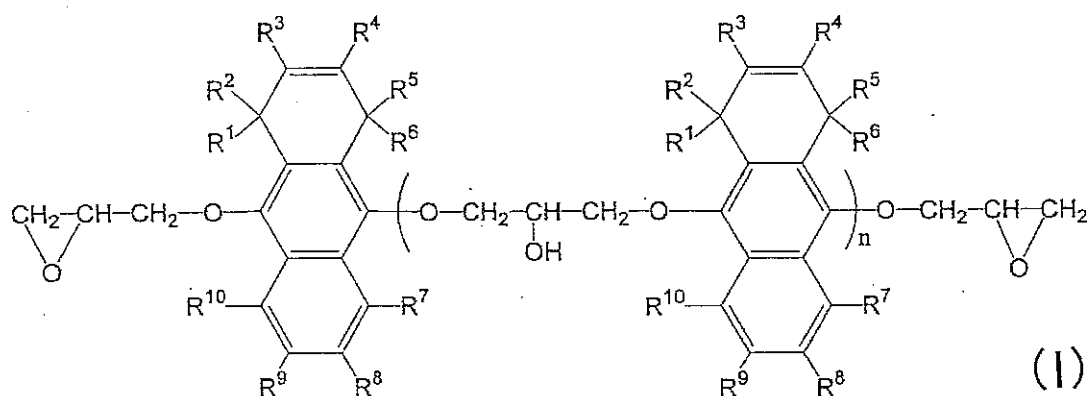


EPOXY COMPOUND, PREPARATION METHOD THEREOF, AND USE THEREOF

ABSTRACT

The present invention relates to an epoxy compound, represented by a general formula (I), which is solid at ordinary temperature, has extremely low melt viscosity and has excellent curing property and which can provide a cured product which is excellent in mechanical strength, heat resistance, and moisture resistance. It also relates to a preparation method of the epoxy compound, an epoxy resin composition, and a cured product thereof. The epoxy compound is represented by the following general formula (I):



(wherein R¹-R¹⁰ each represent hydrogen atom or alkyl group having 1-6 carbon atoms, and n represents an integer of 0 or more).

(no figure to accompany the abstract)